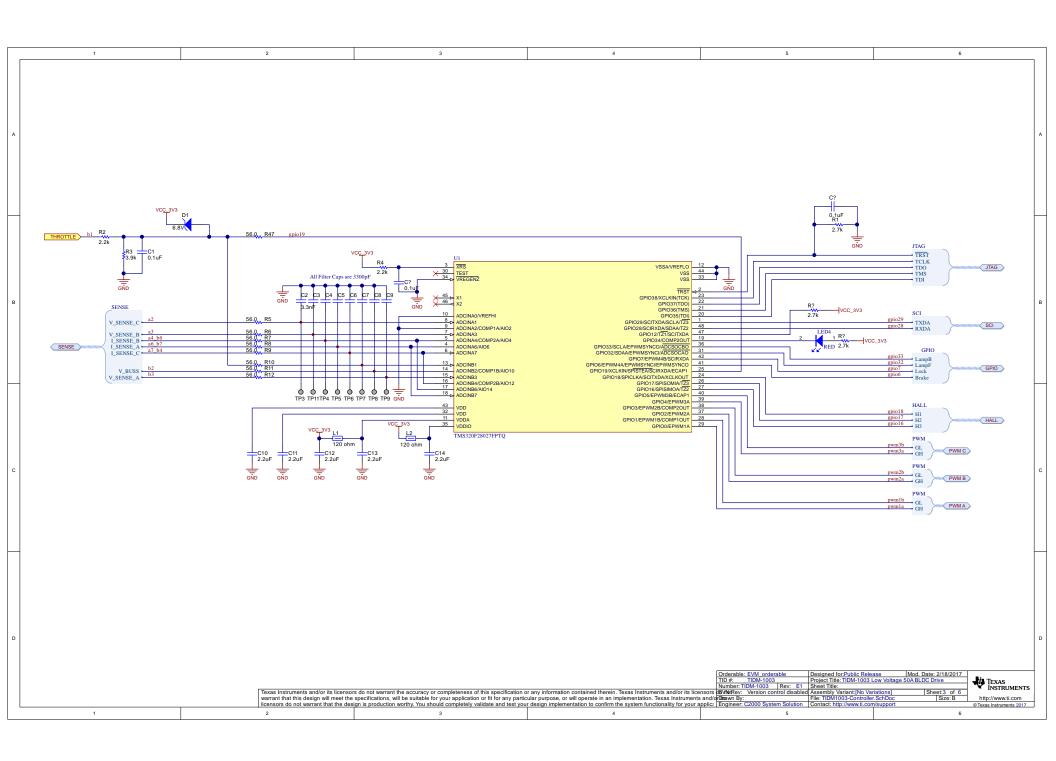
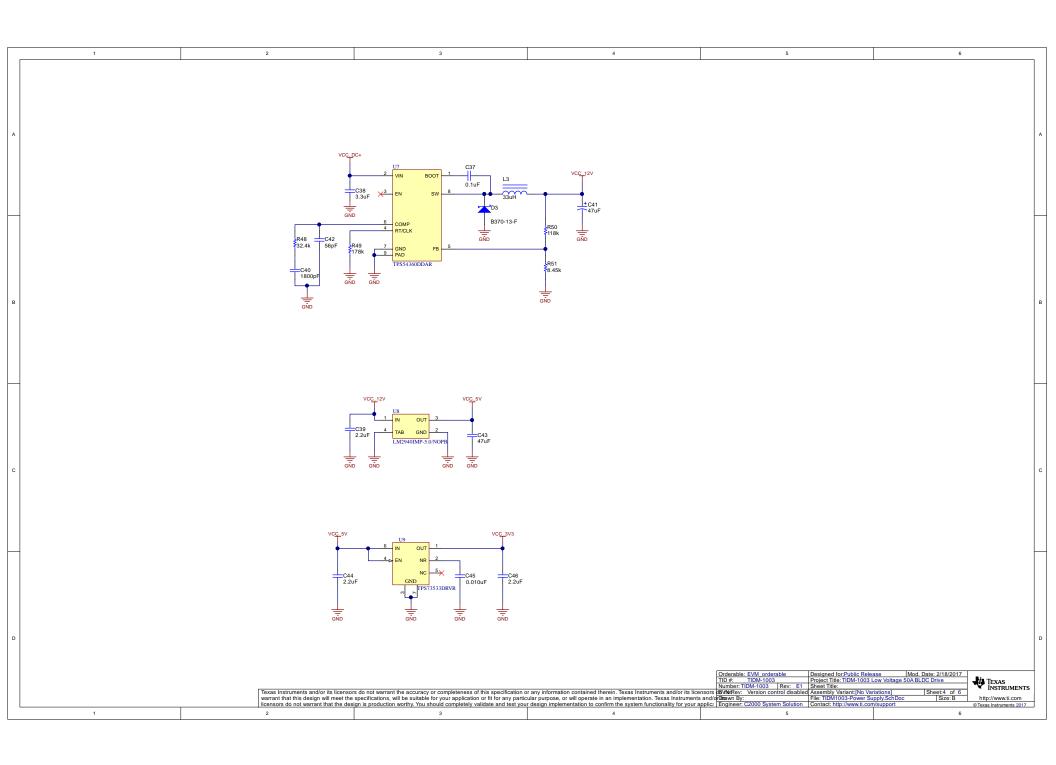


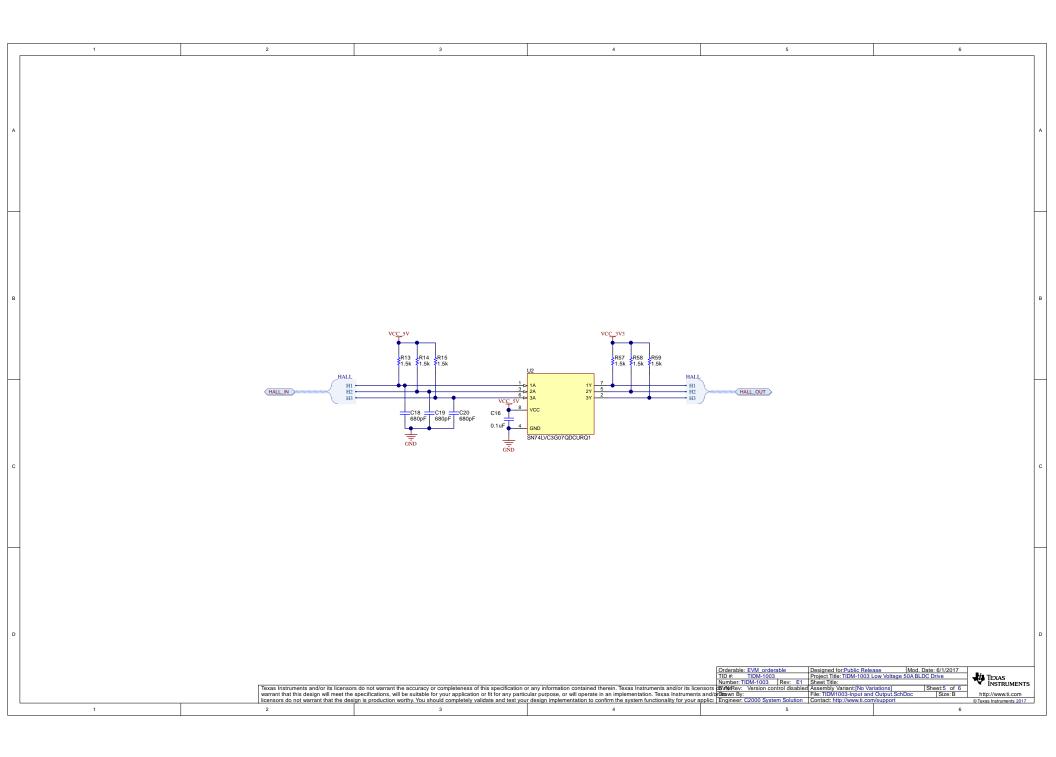
PCB Number: TIDM-1003 PCB Rev: E1 Label Table Variant Label Text 001 Initial Version PCB Label Size: 0.65" x 0.20 " ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed. ZZ3

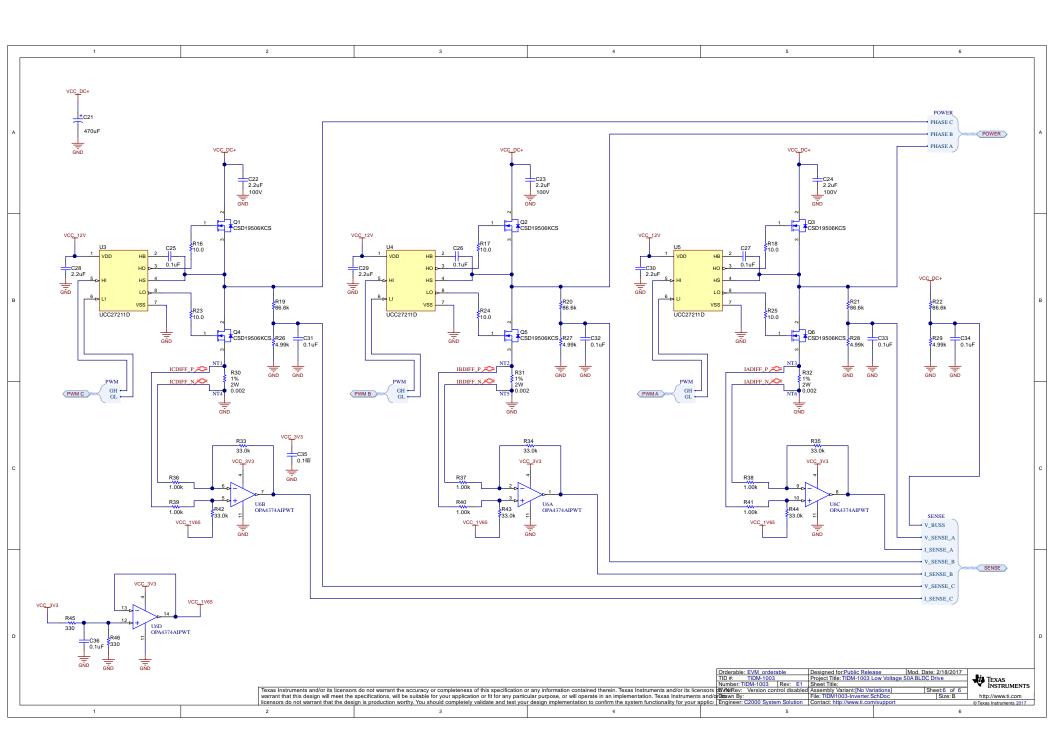
Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable. Z24
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified. Orderable: EVM orderable Designed for Public Release Mod. Date: 2/18/2017
Till 9 : Till 0 + 10 : Til TEXAS INSTRUMENTS Size: B http://www.ti.com









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